### MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

Meets or Exceeds the Requirements of D, N, OR NS PACKAGE (TOP VIEW) ANSI Standards EIA/TIA-422-B and **EIA/TIA-423-B and ITU Recommendations** 1B 16 VCC V.10 and V.11 1A [ 15 AB 3-State, TTL-Compatible Outputs 14 🛮 4A 1Y **∏** 3 **Fast Transition Times** 1.2EN **∏** 4 13 T 4Y **Operates From Single 5-V Supply** 12 3,4EN 2Y 🛮 2A 11 3Y Designed to Be Interchangeable With 2B **∏** 7 10 3A Motorola™ MC3486 9 1 3B GND

#### description

The MC3486 is a monolithic quadruple differential line receiver designed to meet the specifications of ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B and ITU Recommendations V.10 and V.11. The MC3486 offers four independent differential-input line receivers that have TTL-compatible outputs. The outputs utilize 3-state circuitry to provide a high-impedance state at any output when the appropriate output enable is at a low logic level.

The MC3486 is designed for optimum performance when used with the MC3487 quadruple differential line driver. It is supplied in a 16-pin package and operates from a single 5-V supply.

The MC3486 is characterized for operation from 0°C to 70°C.

#### **AVAILABLE OPTIONS**

|             | PACKAGED D                          | EVICES                |  |  |
|-------------|-------------------------------------|-----------------------|--|--|
| TA          | PLASTIC<br>SMALL OUTLINE<br>(D, NS) | PLASTIC<br>DIP<br>(N) |  |  |
| 0°C to 70°C | MC3486D<br>MC3486NS                 | MC3486N               |  |  |

The D package is available taped and reeled. Add the suffix R to the device type (e.g., MC3486DR). The NS package is only available taped and reeled.



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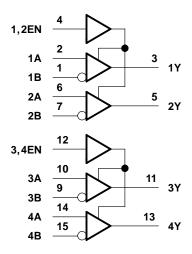


## FUNCTION TABLE (each receiver)

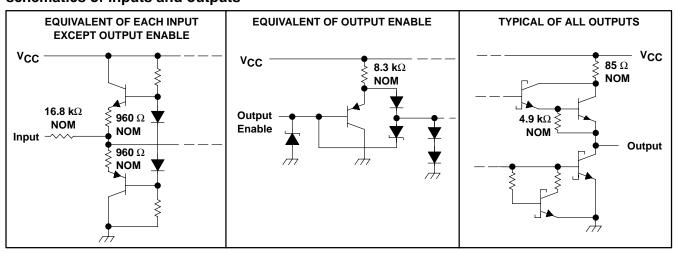
| DIFFERENTIAL INPUTS<br>A-B                              | ENABLE | OUTPUT<br>Y |
|---|--------|-------------|
| V <sub>ID</sub> ≤ 0.2 V                                 | Н      | Н           |
| $-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$ | Н      | ?           |
| $V_{ID} \le -0.2 V$                                     | Н      | L           |
| Irrelevant  | L      | Z           |
| Open  | Н      | ?           |

H = high level, L = low level, Z = high impedance (off), ? = indeterminate

#### logic diagram (positive logic)



#### schematics of inputs and outputs





### MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage, V <sub>CC</sub> (see Note 1)                       | 8 V            |
|--|----------------|
| Input voltage, V <sub>I</sub> (A or B inputs)                      |                |
| Differential input voltage, V <sub>ID</sub> (see Note 2)           |                |
| Enable input voltage   | 8 V            |
| Low-level output current, IOL                                      |                |
| Package thermal impedance, θ <sub>JA</sub> (see Note 3): D package |                |
| N package  | 67°C/W         |
| NS package   | 67°C/W         |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds       | 260°C          |
| Storage temperature range, T <sub>stg</sub>                        | –65°C to 150°C |

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential-input voltage, are with respect to network ground terminal.
  - 2. Differential-input voltage is measured at the noninverting input with respect to the corresponding inverting input.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions

|     |                                 | MIN  | NOM | MAX  | UNIT |
|-----|---------------------------------|------|-----|------|------|
| VCC | Supply voltage                  | 4.75 | 5   | 5.25 | V    |
| VIC | Common-mode input voltage       |      |     | ±7   | V    |
| VID | Differential input voltage      |      |     | ±6   | V    |
| VIH | High-level enable input voltage | 2    |     |      | V    |
| VIL | Low-level enable input voltage  |      |     | 0.8  | V    |
| TA  | Operating free-air temperature  | 0    |     | 70   | °C   |

## MC3486 QUADRUPLE DIFFERENTIAL LINE RECEIVER WITH 3-STATE OUTPUTS

SLLS097C - JUNE 1980 - REVISED FEBRUARY 2002

# electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

|                  | PARAMETER                                 | TEST CONDITION  | s                       | MIN   | MAX   | UNIT |
|------------------|---|---|-------------------------|-------|-------|------|
| V <sub>IT+</sub> | Differential input high-threshold voltage | $V_0 = 2.7 \text{ V}, \qquad I_0 = -0.4 \text{ mA}$   |                         |       | 0.2   | V    |
| $V_{IT-}$        | Differential input low-threshold voltage  | $V_{O} = 0.5 \text{ V}, \qquad I_{O} = -8 \text{ mA}$   |                         | -0.2† |       | V    |
| $V_{IK}$         | Enable-input clamp voltage                | $I_{\parallel} = -10 \text{ mA}$  |                         |       | -1.5  | V    |
| Vон              | High-level output voltage                 | $V_{\text{ID}}$ = 0.4 V, $I_{\text{O}}$ = -0.4 mA, See Note 4 and Figure 1                    |                         | 2.7   |       | ٧    |
| VOL              | Low-level output voltage                  | $V_{\text{ID}} = -0.4 \text{ V}, \qquad I_{\text{O}} = 8 \text{ mA},$ See Note 4 and Figure 1 |                         |       | 0.5   | ٧    |
| 1                | High-impedance-state output current       | $V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = -3 \text{ V},$                                       | V <sub>O</sub> = 2.7 V  |       | 40    |      |
| loz              | nigh-impedance-state output current       | $V_{IL} = 0.8 \text{ V}, \qquad V_{ID} = 3 \text{ V},$  | $V_0 = 0.5 \text{ V}$   |       | -40   | μΑ   |
|                  |   |   | $V_{I} = -10 \text{ V}$ |       | -3.25 |      |
|                  | Differential-input bias current           | V <sub>CC</sub> = 0 V or 5.25 V,  | $V_I = -3 V$            |       | -1.5  | m A  |
| IВ               | Differential-input bias current           | Other inputs at 0 V   | V <sub>I</sub> = 3 V    | 1.5   |       | mA   |
|                  |   |   | V <sub>I</sub> = 10 V   |       | 3.25  |      |
| 1                | High-level enable input current           | V <sub>I</sub> = 5.25 V   |                         | 100   |       |      |
| lιΗ              | nigir-ievei enable in <b>p</b> ut current | V <sub>I</sub> = 2.7 V  |                         | 20    | μΑ    |      |
| IլL              | Low-level enable input current            | V <sub>I</sub> = -0.5 V   |                         |       | -100  | μΑ   |
| los              | Short-circuit output current              | $V_{ID} = 3 V, V_{O} = 0,$  | See Note 5              | -15   | -100  | mA   |
| ICC              | Supply current                            | V <sub>IL</sub> = 0   | •                       |       | 85    | mA   |

<sup>†</sup> The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet for threshold voltages only.

NOTES: 4. Refer to ANSI Standards TIA/EIA-422-B and TIA/EIA-423-B for exact conditions.

5. Only one output should be shorted at a time.

## switching characteristics, $V_{CC}$ = 5 V, $C_L$ = 15 pF, $T_A$ = 25°C

|                  | PARAMETER   | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|---|-----------------|-----|-----|-----|------|
| tPHL             | Propagation delay time, high- to low-level output | See Figure 2    |     | 28  | 35  | ns   |
| tPLH             | Propagation delay time, low- to high-level output | See Figure 2    |     | 27  | 30  | ns   |
| <sup>t</sup> PZH | Output enable time to high level                  |                 |     | 13  | 30  | ns   |
| tPZL             | Output enable time to low level                   | See Figure 3    |     | 20  | 30  | ns   |
| tPHZ             | Output disable time from high level               | See Figure 3    |     | 26  | 35  | ns   |
| <sup>t</sup> PLZ | Output disable time from low level                |                 |     | 27  | 35  | ns   |



#### PARAMETER MEASUREMENT INFORMATION

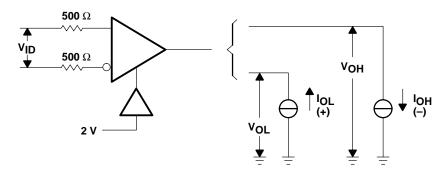
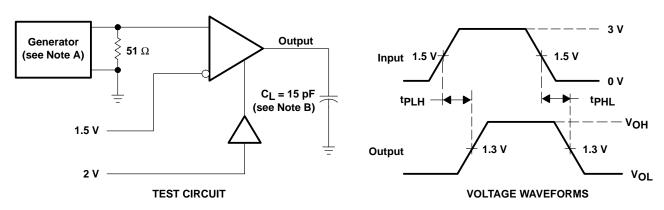


Figure 1. V<sub>OH</sub>, V<sub>OL</sub>

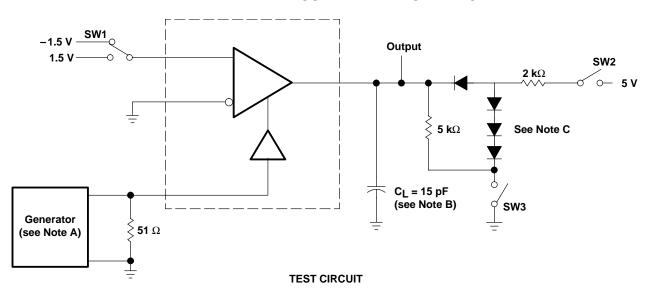


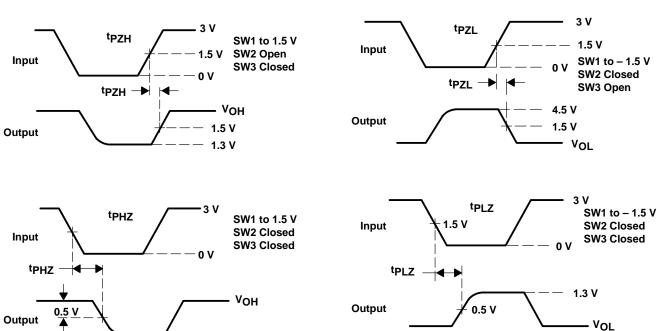
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, duty cycle = 50%,  $t_{f} \leq$  6 ns,  $t_{f} \leq$  6 ns.

B. C<sub>L</sub> includes probe and stray capacitance.

Figure 2. Test Circuit and Voltage Waveforms

#### PARAMETER MEASUREMENT INFORMATION





NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, duty cycle = 50%,  $t_f \leq$  6 ns,  $t_f \leq$  6 ns.

B. CL includes probe and stray capacitance.

1.3 V

C. All diodes are 1N916 or equivalent.

Figure 3. Test Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

| Orderable Device | Status | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan     | Lead finish/<br>Ball material | MSL Peak Temp      | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|--------|--------------|--------------------|------|----------------|--------------|-------------------------------|--------------------|--------------|----------------------|---------|
| MC3486D          | ACTIVE | SOIC         | D                  | 16   | 40             | RoHS & Green | (6)<br>NIPDAU                 | Level-1-260C-UNLIM | 0 to 70      | MC3486               | Samples |
| MC3486DE4        | ACTIVE | SOIC         | D                  | 16   | 40             | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | MC3486               | Samples |
| MC3486DG4        | ACTIVE | SOIC         | D                  | 16   | 40             | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | MC3486               | Samples |
| MC3486DR         | ACTIVE | SOIC         | D                  | 16   | 2500           | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | MC3486               | Samples |
| MC3486DRE4       | ACTIVE | SOIC         | D                  | 16   | 2500           | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | MC3486               | Samples |
| MC3486N          | ACTIVE | PDIP         | N                  | 16   | 25             | RoHS & Green | NIPDAU                        | N / A for Pkg Type | 0 to 70      | MC3486N              | Samples |
| MC3486NE4        | ACTIVE | PDIP         | N                  | 16   | 25             | RoHS & Green | NIPDAU                        | N / A for Pkg Type | 0 to 70      | MC3486N              | Samples |
| MC3486NSR        | ACTIVE | SO           | NS                 | 16   | 2000           | RoHS & Green | NIPDAU                        | Level-1-260C-UNLIM | 0 to 70      | MC3486               | Samples |

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



### **PACKAGE OPTION ADDENDUM**

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE MATERIALS INFORMATION**

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#### TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width     |
|----|---|
| В0 | Dimension designed to accommodate the component length    |
| K0 | Dimension designed to accommodate the component thickness |
| W  | Overall width of the carrier tape                         |
| P1 | Pitch between successive cavity centers                   |

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

|   | Device    | _    | Package<br>Drawing |    | SPQ  | Reel<br>Diameter<br>(mm) | Reel<br>Width<br>W1 (mm) | A0<br>(mm) | B0<br>(mm) | K0<br>(mm) | P1<br>(mm) | W<br>(mm) | Pin1<br>Quadrant |
|---|-----------|------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
|   | MC3486DR  | SOIC | D                  | 16 | 2500 | 330.0                    | 16.4                     | 6.5        | 10.3       | 2.1        | 8.0        | 16.0      | Q1               |
| L | MC3486NSR | so   | NS                 | 16 | 2000 | 330.0                    | 16.4                     | 8.2        | 10.5       | 2.5        | 12.0       | 16.0      | Q1               |

**PACKAGE MATERIALS INFORMATION** 

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#### \*All dimensions are nominal

| Device    | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|-----------|--------------|-----------------|------|------|-------------|------------|-------------|
| MC3486DR  | SOIC         | D               | 16   | 2500 | 340.5       | 336.1      | 32.0        |
| MC3486NSR | SO           | NS              | 16   | 2000 | 356.0       | 356.0      | 35.0        |

## **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



\*All dimensions are nominal

| Device    | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|-----------|--------------|--------------|------|-----|--------|--------|--------|--------|
| MC3486D   | D            | SOIC         | 16   | 40  | 507    | 8      | 3940   | 4.32   |
| MC3486DE4 | D            | SOIC         | 16   | 40  | 507    | 8      | 3940   | 4.32   |
| MC3486DG4 | D            | SOIC         | 16   | 40  | 507    | 8      | 3940   | 4.32   |
| MC3486N   | N            | PDIP         | 16   | 25  | 506    | 13.97  | 11230  | 4.32   |
| MC3486N   | N            | PDIP         | 16   | 25  | 506    | 13.97  | 11230  | 4.32   |
| MC3486NE4 | N            | PDIP         | 16   | 25  | 506    | 13.97  | 11230  | 4.32   |
| MC3486NE4 | N            | PDIP         | 16   | 25  | 506    | 13.97  | 11230  | 4.32   |

## D (R-PDS0-G16)

#### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



## D (R-PDSO-G16)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



#### NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



#### NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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